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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I²C, IrDA, SPI, UART/USART, USB, USB OTG
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	66
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 33x16b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mk22fn512vll12r

1. MK22FN512VFX12 (88QFN) does not support the FlexBus function.
2. MK22FN512VFX12 (88QFN) does not support the DAC1 function.

Ordering Information

Part Number	Memory		Maximum number of I/O's
	Flash (KB)	SRAM (KB)	
MK22FN512VDC12	512	128	81
MK22FN512VLL12	512	128	66
MK22FN512VLH12	512	128	40
MK22FN512VMP12	512	128	40
MK22FN512VFX12	512	128	60

Device Revision Number

Device Mask Set Number	SIM_SDID[REVID]	JTAG ID Register[PRN]
0N50M	0001	0001

Related Resources

Type	Description	Document
Selector Guide	The NXP Solution Advisor is a web-based tool that features interactive application wizards and a dynamic product selector	KINETISKMCUSELGD
Product Brief	The Product Brief contains concise overview/summary information to enable quick evaluation of a device for design suitability.	K22FPB
Reference Manual	The Reference Manual contains a comprehensive description of the structure and function (operation) of a device.	K22P121M120SF7RM
Data Sheet	The Data Sheet is this document. It includes electrical characteristics and signal connections.	K22P121M120SF7
Chip Errata	The chip mask set Errata provides additional or corrective information for a particular device mask set.	KINETIS_K_*x*N50M[1]
Package drawing	Package dimensions are provided by part number: • MK22FN512VDC12 • MK22FN512VLL12 • MK22FN512VLH12 • MK22FN512VMP12 • MK22FN512VFX12	Package drawing: • 98ASA00595D • 98ASS23308W • 98ASS23234W • 98ASA00420D • 98ASA00935D
Engineering Bulletin	This engineering bulletin gives connection recommendations specifically for microcontrollers in DFN and QFN packages.	Electrical Connection Recommendations for the Exposed Pad on QFN and DFN Packages.

1. To find the associated resource, go to nxp.com and perform a search using this term with the *x* replaced by the revision of the device you are using.

Figure 1 shows the functional modules in the chip.

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	@ 70°C	—	9.5	21.25	µA	
	@ 85°C	—	15.3	34.65	µA	
	@ 105°C	—	30.1	66.05	µA	
I_{DD_VLLS2}	Very low-leakage stop mode 2 current at 3.0 V					
	@ -40°C to 25°C	—	1.9	2.45	µA	
	@ 70°C	—	4.5	8.50	µA	
	@ 85°C	—	6.8	12.15	µA	
	@ 105°C	—	13.0	25.50	µA	
I_{DD_VLLS1}	Very low-leakage stop mode 1 current at 3.0 V					
	@ -40°C to 25°C	—	0.73	1.42	µA	
	@ 70°C	—	1.8	3.90	µA	
	@ 85°C	—	3.0	5.25	µA	
	@ 105°C	—	5.9	10.80	µA	
I_{DD_VLLS0}	Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit enabled					
	@ -40°C to 25°C	—	0.43	0.55	µA	
	@ 70°C	—	1.4	2.45	µA	
	@ 85°C	—	2.6	4.00	µA	
	@ 105°C	—	5.4	9.30	µA	
I_{DD_VLLS0}	Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit disabled					
	@ -40°C to 25°C	—	0.14	0.24	µA	
	@ 70°C	—	1.1	2.15	µA	
	@ 85°C	—	2.3	3.85	µA	
	@ 105°C	—	5.1	9.00	µA	
I_{DD_VBAT}	Average current with RTC and 32kHz disabled at 3.0 V					
	@ -40°C to 25°C	—	0.18	0.21	µA	
	@ 70°C	—	0.66	0.86	µA	
	@ 85°C	—	1.52	2.24	µA	
	@ 105°C	—	2.92	4.30	µA	
I_{DD_VBAT}	Average current when CPU is not accessing RTC registers					
	@ 1.8V					
	• @ -40°C to 25°C	—	0.59	0.70	µA	15
	• @ 70°C	—	1.00	1.3	µA	
	• @ 85°C	—	1.76	2.59	µA	
	• @ 105°C	—	3.00	4.42	µA	
	@ 3.0V					

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	• @ -40°C to 25°C	—	0.71	0.84	µA	
	• @ 70°C	—	1.22	1.59	µA	
	• @ 85°C	—	2.08	3.06	µA	
	• @ 105°C	—	3.50	5.15	µA	

1. The analog supply current is the sum of the active or disabled current for each of the analog modules on the device. See each module's specification for its supply current.
2. 120MHz core and system clock, 60MHz bus clock, 24MHz FlexBus clock, and 24MHz flash clock. MCG configured for PEE mode. All peripheral clocks disabled.
3. Cache on and prefetch on, low compiler optimization.
4. Coremark benchmark compiled using IAR 7.2 with optimization level low.
5. 120MHz core and system clock, 60MHz bus clock, 24MHz FlexBus clock, and 24MHz flash clock. MCG configured for PEE mode. All peripheral clocks enabled.
6. 80 MHz core and system clock, 40 MHz bus clock, and 26.67 MHz flash clock. MCG configured for PEE mode. Compute operation.
7. 80MHz core and system clock, 40MHz bus clock, 20MHz FlexBus clock, and 26.67MHz flash clock. MCG configured for FEI mode. All peripheral clocks disabled.
8. 80MHz core and system clock, 40MHz bus clock, 20MHz FlexBus clock, and 26.67MHz flash clock. MCG configured for FEI mode. All peripheral clocks enabled.
9. 80MHz core and system clock, 40MHz bus clock, and 26.67MHz flash clock. MCG configured for FEI mode. Compute operation.
10. 25MHz core and system clock, 25MHz bus clock, and 25MHz FlexBus and flash clock. MCG configured for FEI mode.
11. 4 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. Compute operation. Code executing from flash.
12. 4 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled. Code executing from flash.
13. 4 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks enabled but peripherals are not in active operation. Code executing from flash.
14. 4 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled.
15. Includes 32kHz oscillator current and RTC operation.

Table 7. Low power mode peripheral adders—typical value

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105	
$I_{IREFSTEN4MHz}$	4 MHz internal reference clock (IRC) adder. Measured by entering STOP or VLPS mode with 4 MHz IRC enabled.	56	56	56	56	56	56	µA
$I_{IREFSTEN32KHz}$	32 kHz internal reference clock (IRC) adder. Measured by entering STOP mode with the 32 kHz IRC enabled.	52	52	52	52	52	52	µA
$I_{EREFSTEN4MHz}$	External 4 MHz crystal clock adder. Measured by entering STOP or VLPS mode with the crystal enabled.	206	228	237	245	251	258	uA
$I_{EREFSTEN32KHz}$	External 32 kHz crystal clock adder by means of the OSC0_CR[EREFSTEN							

Table continues on the next page...

- MCG in FBE mode for 50 MHz and lower frequencies. MCG in FEE mode at frequencies between 50 MHz and 100MHz. MCG in PEE mode at frequencies greater than 100 MHz.
- USB regulator disabled
- No GPIOs toggled
- Code execution from flash with cache enabled
- For the ALLOFF curve, all peripheral clocks are disabled except FTFA

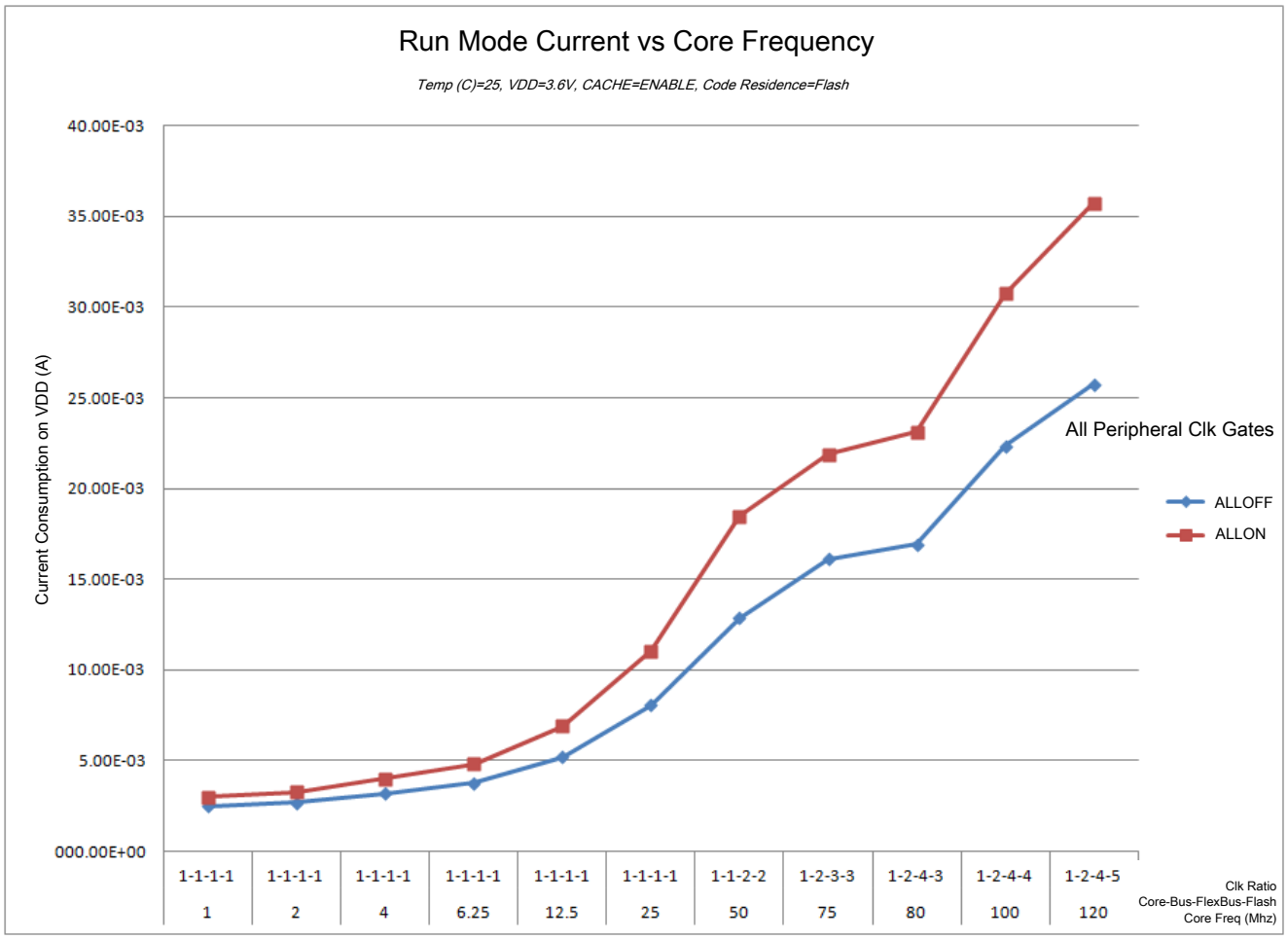

Figure 3. Run mode supply current vs. core frequency

3. The reported emission level is the value of the maximum measured emission, rounded up to the next whole number, from among the measured orientations in each frequency range.
4. IEC Level Maximums: M ≤ 18dBmV, L ≤ 24dBmV, K ≤ 30dBmV, I ≤ 36dBmV, H ≤ 42dBmV .

2.2.7 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

- Go to nxp.com
- Perform a keyword search for "EMC design."

2.2.8 Capacitance attributes

Table 9. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C_{IN_A}	Input capacitance: analog pins	—	7	pF
C_{IN_D}	Input capacitance: digital pins	—	7	pF

2.3 Switching specifications

2.3.1 Device clock specifications

Table 10. Device clock specifications

Symbol	Description	Min.	Max.	Unit	Notes
High Speed run mode					
f_{SYS}	System and core clock	—	120	MHz	
f_{BUS}	Bus clock	—	60	MHz	
Normal run mode (and High Speed run mode unless otherwise specified above)					
f_{SYS}	System and core clock	—	80	MHz	
f_{SYS_USB}	System and core clock when Full Speed USB in operation	20	—	MHz	
f_{BUS}	Bus clock	—	50	MHz	
FB_CLK	FlexBus clock	—	30	MHz	
f_{FLASH}	Flash clock	—	26.67	MHz	
f_{LPTMR}	LPTMR clock	—	25	MHz	
VLPR mode[1]					

Table continues on the next page...

3.3.1 MCG specifications

Table 16. MCG specifications

Symbol	Description		Min.	Typ.	Max.	Unit	Notes
f_{ints_ft}	Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25 °C		—	32.768	—	kHz	
Δf_{ints_t}	Total deviation of internal reference frequency (slow clock) over voltage and temperature		—	+0.5/-0.7	± 2	%	
f_{ints_t}	Internal reference frequency (slow clock) — user trimmed		31.25	—	39.0625	kHz	
$\Delta_{fdco\_res\_t}$	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM		—	± 0.3	± 0.6	$\%f_{dco}$	1
Δf_{dco_t}	Total deviation of trimmed average DCO output frequency over voltage and temperature		—	+0.5/-0.7	± 2	$\%f_{dco}$	1, 2
Δf_{dco_t}	Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C		—	± 0.3	± 1.5	$\%f_{dco}$	1
f_{intf_ft}	Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C		—	4	—	MHz	
Δf_{intf_ft}	Frequency deviation of internal reference clock (fast clock) over temperature and voltage — factory trimmed at nominal VDD and 25 °C		—	+1/-2	± 5	$\%f_{intf\_ft}$	
f_{intf_t}	Internal reference frequency (fast clock) — user trimmed at nominal VDD and 25 °C		3	—	5	MHz	
f_{loc_low}	Loss of external clock minimum frequency — RANGE = 00		(3/5) x f_{ints_t}	—	—	kHz	
f_{loc_high}	Loss of external clock minimum frequency — RANGE = 01, 10, or 11		(16/5) x f_{ints_t}	—	—	kHz	
FLL							
f_{fll_ref}	FLL reference frequency range		31.25	—	39.0625	kHz	
f_{dco}	DCO output frequency range	Low range (DRS=00) 640 × f_{fll_ref}	20	20.97	25	MHz	3, 4
		Mid range (DRS=01) 1280 × f_{fll_ref}	40	41.94	50	MHz	
		Mid-high range (DRS=10) 1920 × f_{fll_ref}	60	62.91	75	MHz	
		High range (DRS=11) 2560 × f_{fll_ref}	80	83.89	100	MHz	
$f_{dco\_t\_DMX32}$	DCO output frequency	Low range (DRS=00) 732 × f_{fll_ref}	—	23.99	—	MHz	5, 6
		Mid range (DRS=01) 1464 × f_{fll_ref}	—	47.97	—	MHz	
		Mid-high range (DRS=10)	—	71.99	—	MHz	

Table continues on the next page...

Table 16. MCG specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	$2197 \times f_{fll\_ref}$					
	High range (DRS=11) $2929 \times f_{fll\_ref}$	—	95.98	—	MHz	
J_{cyc_fll}	FLL period jitter • f_{VCO} = 48 MHz • f_{VCO} = 98 MHz	— —	— 180 150	— —	ps	
$t_{fll\_acquire}$	FLL target frequency acquisition time	—	—	1	ms	7
PLL						
f_{vco}	VCO operating frequency	48.0	—	120	MHz	
I_{pll}	PLL operating current • PLL @ 96 MHz ($f_{osc\_hi\_1}$ = 8 MHz, f_{pll_ref} = 2 MHz, VDIV multiplier = 48)	—	1060	—	µA	8
I_{pll}	PLL operating current • PLL @ 48 MHz ($f_{osc\_hi\_1}$ = 8 MHz, f_{pll_ref} = 2 MHz, VDIV multiplier = 24)	—	600	—	µA	8
f_{pll_ref}	PLL reference frequency range	2.0	—	4.0	MHz	
J_{cyc_pll}	PLL period jitter (RMS) • f_{vco} = 48 MHz • f_{vco} = 100 MHz	— —	120 75	— —	ps ps	9
J_{acc_pll}	PLL accumulated jitter over 1µs (RMS) • f_{vco} = 48 MHz • f_{vco} = 100 MHz	— —	1350 600	— —	ps ps	9
D_{lock}	Lock entry frequency tolerance	± 1.49	—	± 2.98	%	
D_{unl}	Lock exit frequency tolerance	± 4.47	—	± 5.97	%	
t_{pll_lock}	Lock detector detection time	—	—	$150 \times 10^{-6} + 1075(1/f_{pll\_ref})$	s	10

1. This parameter is measured with the internal reference (slow clock) being used as a reference to the FLL (FEI clock mode).
2. 2.0 V <= VDD <= 3.6 V.
3. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=0.
4. The resulting system clock frequencies should not exceed their maximum specified values. The DCO frequency deviation (Δf_{dco_t}) over voltage and temperature should be considered.
5. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=1.
6. The resulting clock frequency must not exceed the maximum specified clock frequency of the device.
7. This specification applies to any time the FLL reference source or reference divider is changed, trim value is changed, DMX32 bit is changed, DRS bits are changed, or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.
8. Excludes any oscillator currents that are also consuming power while PLL is in operation.
9. This specification was obtained using a NXP developed PCB. PLL jitter is dependent on the noise characteristics of each PCB and results will vary.
10. This specification applies to any time the PLL VCO divider or reference divider is changed, or changing from PLL disabled (BLPE, BLPI) to PLL enabled (PBE, PEE). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

3.3.2 IRC48M specifications

Table 17. IRC48M specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.71	—	3.6	V	
I_{DD48M}	Supply current	—	400	500	µA	
f_{irc48m}	Internal reference frequency	—	48	—	MHz	
$\Delta f_{irc48m\_ol\_hv}$	Open loop total deviation of IRC48M frequency at high voltage (VDD=1.89V-3.6V) over 0°C to 70°C	—				
	Regulator enable (USB_CLK_RECOVER_IRC_EN[REG_EN]=1)	—	± 0.2	± 0.5	$\%f_{irc48m}$	1
$\Delta f_{irc48m\_ol\_hv}$	Open loop total deviation of IRC48M frequency at high voltage (VDD=1.89V-3.6V) over full temperature					
	Regulator enable (USB_CLK_RECOVER_IRC_EN[REG_EN]=1)	—	± 0.4	± 1.0	$\%f_{irc48m}$	1
$\Delta f_{irc48m\_ol\_lv}$	Open loop total deviation of IRC48M frequency at low voltage (VDD=1.71V-1.89V) over full temperature					1
	Regulator disable (USB_CLK_RECOVER_IRC_EN[REG_EN]=0)	—	± 0.4	± 1.0	$\%f_{irc48m}$	
	Regulator enable (USB_CLK_RECOVER_IRC_EN[REG_EN]=1)	—	± 0.5	± 1.5		
Δf_{irc48m_cl}	Closed loop total deviation of IRC48M frequency over voltage and temperature	—	—	± 0.1	$\%f_{host}$	2
J_{cyc_irc48m}	Period Jitter (RMS)	—	35	150	ps	
$t_{irc48mst}$	Startup time	—	2	3	µs	3

1. The maximum value represents characterized results equivalent to the mean plus or minus three times the standard deviation (mean ± 3 sigma).
2. Closed loop operation of the IRC48M is only feasible for USB device operation; it is not usable for USB host operation. It is enabled by configuring for USB Device, selecting IRC48M as USB clock source, and enabling the clock recover function (USB_CLK_RECOVER_IRC_CTRL[CLOCK_RECOVER_EN]=1, USB_CLK_RECOVER_IRC_EN[IRC_EN]=1).
3. IRC48M startup time is defined as the time between clock enablement and clock availability for system use. Enable the clock by one of the following settings:
   - USB_CLK_RECOVER_IRC_EN[IRC_EN]=1 or
   - MCG operating in an external clocking mode and MCG_C7[OSCSEL]=10 or MCG_C5[PLLCLKEN0]=1, or
   - SIM_SOPT2[PLLFLLSEL]=11

3.3.3 Oscillator electrical specifications

4. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

3.3.4 32 kHz oscillator electrical characteristics

3.3.4.1 32 kHz oscillator DC electrical specifications

Table 20. 32kHz oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V_{BAT}	Supply voltage	1.71	—	3.6	V
R_F	Internal feedback resistor	—	100	—	MΩ
C_{para}	Parasitical capacitance of EXTAL32 and XTAL32	—	5	7	pF
V_{pp}[1]	Peak-to-peak amplitude of oscillation	—	0.6	—	V

1. When a crystal is being used with the 32 kHz oscillator, the EXTAL32 and XTAL32 pins should only be connected to required oscillator components and must not be connected to any other devices.

3.3.4.2 32 kHz oscillator frequency specifications

Table 21. 32 kHz oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal	—	32.768	—	kHz	
t_{start}	Crystal start-up time	—	1000	—	ms	1
$f_{ec\_extal32}$	Externally provided input clock frequency	—	32.768	—	kHz	2
$v_{ec\_extal32}$	Externally provided input clock amplitude	700	—	V_{BAT}	mV	2, 3

1. Proper PC board layout procedures must be followed to achieve specifications.
2. This specification is for an externally supplied clock driven to EXTAL32 and does not apply to any other clock input. The oscillator remains enabled and XTAL32 must be left unconnected.
3. The parameter specified is a peak-to-peak value and V_{IH} and V_{IL} specifications do not apply. The voltage of the applied clock must be within the range of V_{SS} to V_{BAT}.

3.4 Memories and memory interfaces

3.4.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

3.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 22. NVM program/erase timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{hvpgm4}	Longword Program high-voltage time	—	7.5	18	µs	—
$t_{hversscr}$	Sector Erase high-voltage time	—	13	113	ms	1
$t_{hversblk256k}$	Erase Block high-voltage time for 256 KB	—	104	904	ms	1

1. Maximum time based on expectations at cycling end-of-life.

3.4.1.2 Flash timing specifications — commands

Table 23. Flash command timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{rd1blk256k}$	Read 1s Block execution time • 256 KB program flash	—	—	1.7	ms	1
$t_{rd1sec2k}$	Read 1s Section execution time (flash sector)	—	—	60	µs	1
t_{pgmchk}	Program Check execution time	—	—	45	µs	1
t_{rdrsrc}	Read Resource execution time	—	—	30	µs	1
t_{pgm4}	Program Longword execution time	—	65	145	µs	—
$t_{ersblk256k}$	Erase Flash Block execution time • 256 KB program flash	—	250	1500	ms	2
t_{ersscr}	Erase Flash Sector execution time	—	14	114	ms	2
t_{rd1all}	Read 1s All Blocks execution time	—	—	1.8	ms	1
t_{rdonce}	Read Once execution time	—	—	30	µs	1
$t_{pgmonce}$	Program Once execution time	—	100	—	µs	—
t_{ersall}	Erase All Blocks execution time	—	500	3000	ms	2
t_{vfykey}	Verify Backdoor Access Key execution time	—	—	30	µs	1

1. Assumes 25 MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

3.4.1.3 Flash high voltage current behaviors

Table 24. Flash high voltage current behaviors

Symbol	Description	Min.	Typ.	Max.	Unit
I_{DD_PGM}	Average current adder during high voltage flash programming operation	—	2.5	6.0	mA

Table continues on the next page...

2. Specification is valid for all FB_AD[31:0] and FB_TA.

Table 28. Flexbus full voltage range switching specifications

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	1.71	3.6	V	
	Frequency of operation	—	30	MHz	
FB1	Clock period	33.3	—	ns	
FB2	Address, data, and control output valid	—	21.5	ns	
FB3	Address, data, and control output hold	–1.0	—	ns	1
FB4	Data and FB_TA input setup	20.0	—	ns	
FB5	Data and FB_TA input hold	0.5	—	ns	2

1. Specification is valid for all FB_AD[31:0], FB_BE/BWE*n*, FB_CS*n*, FB_OE, FB_R/W,FB_TBST, FB_TSIZ[1:0], FB_ALE, and FB_TS.
2. Specification is valid for all FB_AD[31:0] and FB_TA.

Table 30. 16-bit ADC characteristics (V_{REFH} = V_{DDA}, V_{REFL} = V_{SSA}) (continued)

Symbol	Description	Conditions[1]	Min.	Typ.[2]	Max.	Unit	Notes
		• Avg = 32					
E_{IL}	Input leakage error		$I_{In} \times R_{AS}$			mV	I_{In} = leakage current (refer to the MCU's voltage and current operating ratings)
	Temp sensor slope	Across the full temperature range of the device	1.55	1.62	1.69	mV/°C	8
V_{TEMP25}	Temp sensor voltage	25 °C	706	716	726	mV	8

1. All accuracy numbers assume the ADC is calibrated with V_{REFH} = V_{DDA}
2. Typical values assume V_{DDA} = 3.0 V, Temp = 25 °C, f_{ADCK} = 2.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
4. 1 LSB = (V_{REFH} - V_{REFL})/2^N
5. ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
6. Input data is 100 Hz sine wave. ADC conversion clock < 12 MHz.
7. Input data is 1 kHz sine wave. ADC conversion clock < 12 MHz.
8. ADC conversion clock < 3 MHz

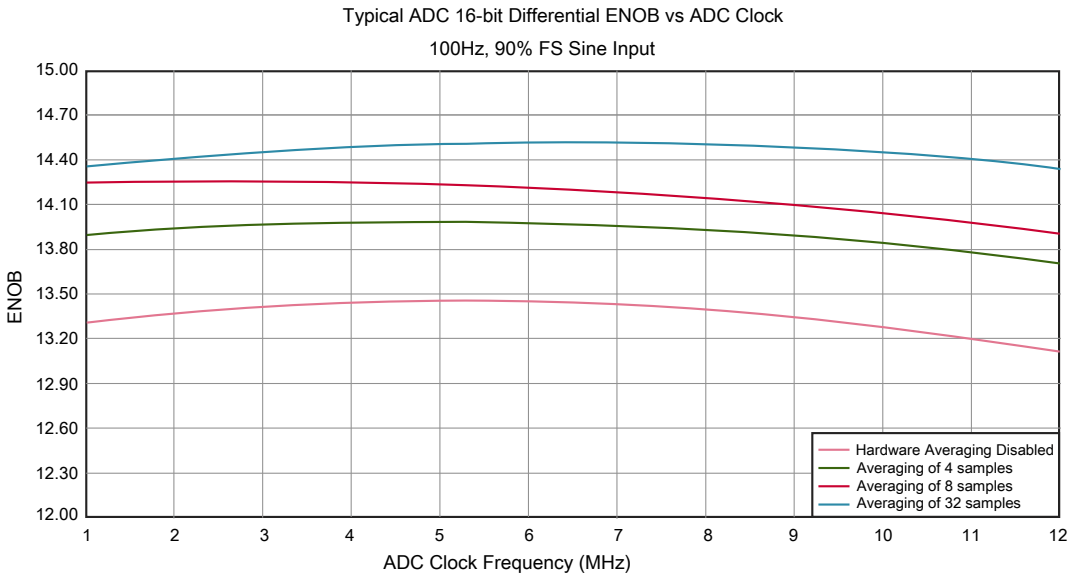

Figure 15. Typical ENOB vs. ADC_CLK for 16-bit differential mode

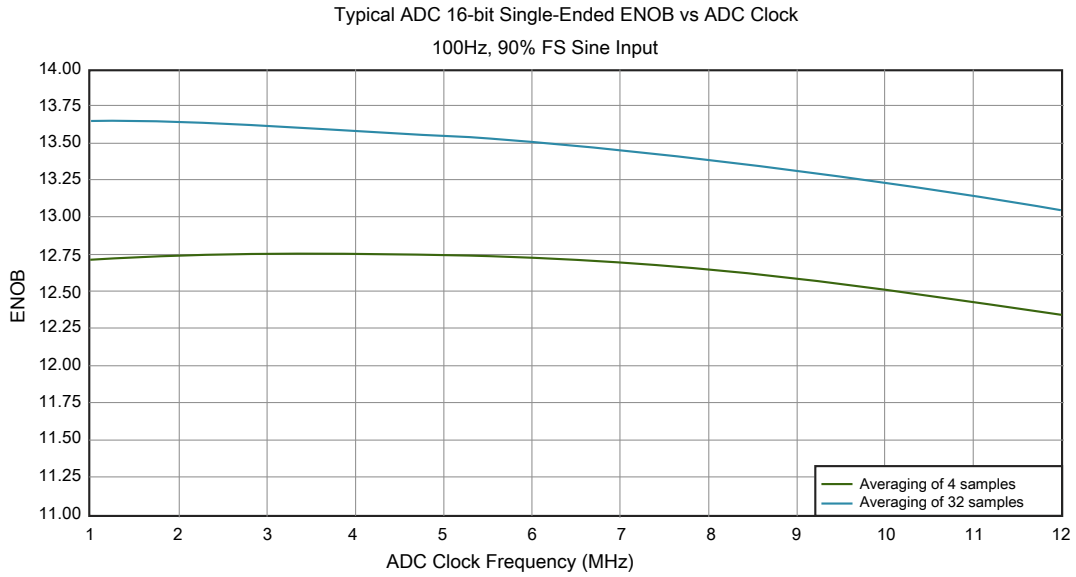

Figure 16. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode

3.6.2 CMP and 6-bit DAC electrical specifications

Table 31. Comparator and 6-bit DAC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V_{DD}	Supply voltage	1.71	—	3.6	V
I_{DDHS}	Supply current, High-speed mode (EN=1, PMODE=1)	—	—	200	µA
I_{DDLS}	Supply current, low-speed mode (EN=1, PMODE=0)	—	—	20	µA
V_{AIN}	Analog input voltage	V_{SS} – 0.3	—	V_{DD}	V
V_{AIO}	Analog input offset voltage	—	—	20	mV
V_H	Analog comparator hysteresis[1]				
	• CR0[HYSTCTR] = 00	—	5	—	mV
	• CR0[HYSTCTR] = 01	—	10	—	mV
	• CR0[HYSTCTR] = 10	—	20	—	mV
	• CR0[HYSTCTR] = 11	—	30	—	mV
V_{CMPOh}	Output high	V_{DD} – 0.5	—	—	V
V_{CMPOl}	Output low	—	—	0.5	V
t_{DHS}	Propagation delay, high-speed mode (EN=1, PMODE=1)	20	50	200	ns
t_{DLS}	Propagation delay, low-speed mode (EN=1, PMODE=0)	80	250	600	ns
	Analog comparator initialization delay[2]	—	—	40	µs
I_{DAC6b}	6-bit DAC current adder (enabled)	—	7	—	µA
INL	6-bit DAC integral non-linearity	–0.5	—	0.5	LSB[3]
DNL	6-bit DAC differential non-linearity	–0.3	—	0.3	LSB

Table 47. I2S/SAI master mode timing in Normal Run, Wait and Stop modes (full voltage range) (continued)

Num.	Characteristic	Min.	Max.	Unit
S3	I2S_TX_BCLK/I2S_RX_BCLK cycle time (output)	80	—	ns
S4	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low	45%	55%	BCLK period
S5	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid	—	15	ns
S6	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid	-1.0	—	ns
S7	I2S_TX_BCLK to I2S_TXD valid	—	15	ns
S8	I2S_TX_BCLK to I2S_TXD invalid	0	—	ns
S9	I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK	27	—	ns
S10	I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK	0	—	ns

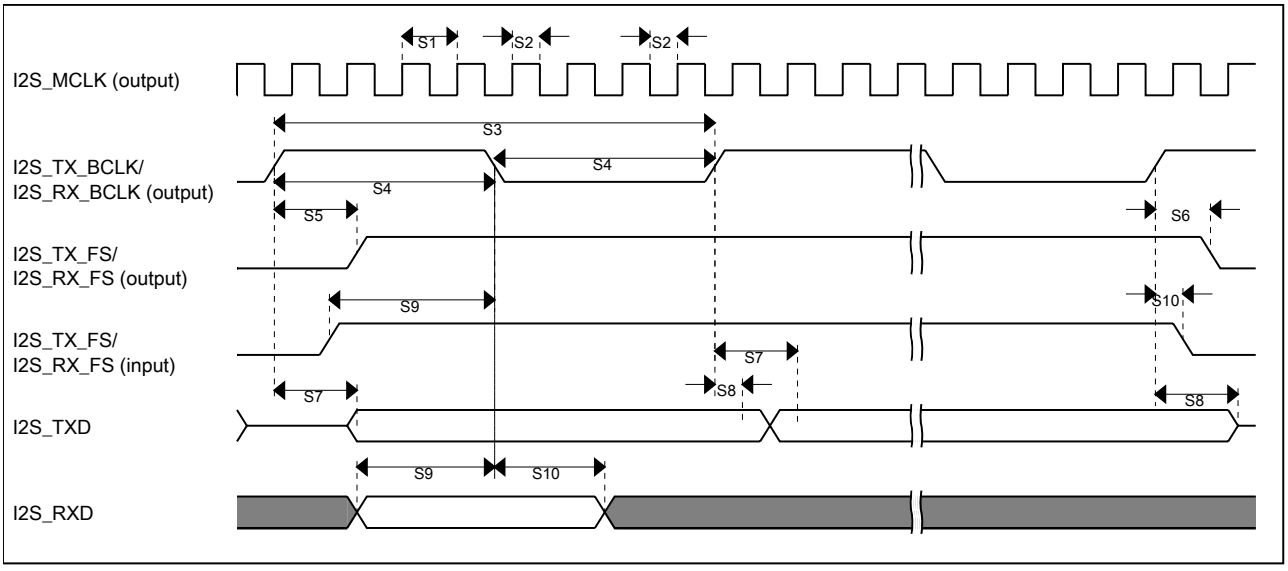

Figure 28. I2S/SAI timing — master modes

Table 48. I2S/SAI slave mode timing in Normal Run, Wait and Stop modes (full voltage range)

Num.	Characteristic	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
S11	I2S_TX_BCLK/I2S_RX_BCLK cycle time (input)	80	—	ns
S12	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low (input)	45%	55%	MCLK period
S13	I2S_TX_FS/I2S_RX_FS input setup before I2S_TX_BCLK/I2S_RX_BCLK	5.8	—	ns

Table continues on the next page...

Table 50. I2S/SAI slave mode timing in VLPR, VLPW, and VLPS modes (full voltage range) (continued)

Num.	Characteristic	Min.	Max.	Unit
S16	I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output invalid	0	—	ns
S17	I2S_RXD setup before I2S_RX_BCLK	30	—	ns
S18	I2S_RXD hold after I2S_RX_BCLK	4	—	ns
S19	I2S_TX_FS input assertion to I2S_TXD output valid[1]	—	72	ns

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

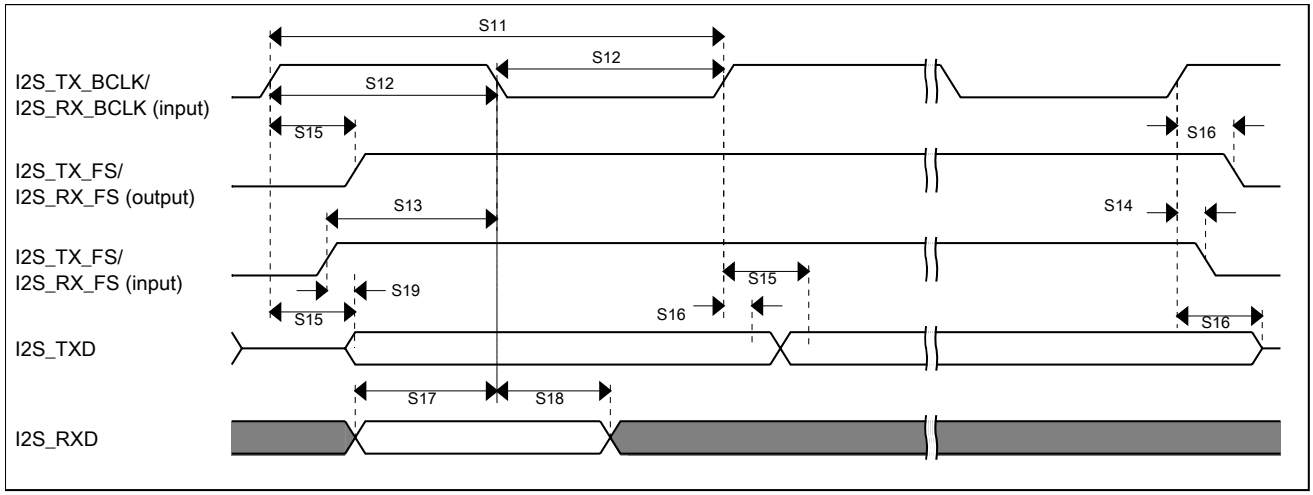

Figure 31. I2S/SAI timing — slave modes

4 Dimensions

4.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to nxp.com and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
64-pin LQFP	98ASS23234W
64-pin MAPBGA	98ASA00420D
88-pin QFN	98ASA00935D

Table continues on the next page...

64 MAP BGA	64 LQFP	88 QFN	100 LQFP	121 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EZPORT
—	—	—	14	H1	ADC0_ DP1	ADC0_ DP1	ADC0_ DP1								
—	—	—	15	H2	ADC0_ DM1	ADC0_ DM1	ADC0_ DM1								
—	—	14	16	J1	ADC1_ DP1/ ADC0_ DP2	ADC1_ DP1/ ADC0_ DP2	ADC1_ DP1/ ADC0_ DP2								
—	—	15	17	J2	ADC1_ DM1/ ADC0_ DM2	ADC1_ DM1/ ADC0_ DM2	ADC1_ DM1/ ADC0_ DM2								
G1	9	16	18	K1	ADC0_ DP0/ ADC1_ DP3	ADC0_ DP0/ ADC1_ DP3	ADC0_ DP0/ ADC1_ DP3								
F1	10	17	19	K2	ADC0_ DM0/ ADC1_ DM3	ADC0_ DM0/ ADC1_ DM3	ADC0_ DM0/ ADC1_ DM3								
G2	11	—	20	L1	ADC1_ DP0/ ADC0_ DP3	ADC1_ DP0/ ADC0_ DP3	ADC1_ DP0/ ADC0_ DP3								
F2	12	—	21	L2	ADC1_ DM0/ ADC0_ DM3	ADC1_ DM0/ ADC0_ DM3	ADC1_ DM0/ ADC0_ DM3								
F4	13	18	22	F5	VDDA	VDDA	VDDA								
G4	14	19	23	G5	VREFH	VREFH	VREFH								
G3	15	20	24	G6	VREFL	VREFL	VREFL								
F3	16	21	25	F6	VSSA	VSSA	VSSA								
—	—	—	—	J3	ADC1_ SE16/ ADC0_ SE22	ADC1_ SE16/ ADC0_ SE22	ADC1_ SE16/ ADC0_ SE22								
—	—	—	—	H3	ADC0_ SE16/ CMP1_ IN2/ ADC0_ SE21	ADC0_ SE16/ CMP1_ IN2/ ADC0_ SE21	ADC0_ SE16/ CMP1_ IN2/ ADC0_ SE21								
H1	17	22	26	L3	VREF_ OUT/ CMP1_ IN5/ CMP0_ IN5/	VREF_ OUT/ CMP1_ IN5/ CMP0_ IN5/	VREF_ OUT/ CMP1_ IN5/ CMP0_ IN5/								

64 MAP BGA	64 LQFP	88 QFN	100 LQFP	121 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EZPORT
—	—	53	57	E10	PTB9	DISABLED		PTB9	SPI1_ PCS1	LPUART0 _CTS_b		FB_AD20			
—	—	54	58	D10	PTB10	ADC1_ SE14	ADC1_ SE14	PTB10	SPI1_ PCS0	LPUART0 _RX		FB_AD19	FTM0_ FLT1		
—	—	55	59	C10	PTB11	ADC1_ SE15	ADC1_ SE15	PTB11	SPI1_SCK	LPUART0 _TX		FB_AD18	FTM0_ FLT2		
—	—	—	60	—	VSS	VSS	VSS								
—	—	—	61	—	VDD	VDD	VDD								
E6	39	56	62	B10	PTB16	DISABLED		PTB16	SPI1_ SOUT	UART0_ RX	FTM_ CLKIN0	FB_AD17	EWM_IN		
D7	40	57	63	E9	PTB17	DISABLED		PTB17	SPI1_SIN	UART0_ TX	FTM_ CLKIN1	FB_AD16	EWM_ OUT_b		
D6	41	58	64	D9	PTB18	DISABLED		PTB18		FTM2_ CH0	I2S0_TX_ BCLK	FB_AD15	FTM2_ QD_PHA		
C7	42	59	65	C9	PTB19	DISABLED		PTB19		FTM2_ CH1	I2S0_TX_ FS	FB_OE_b	FTM2_ QD_PHB		
—	—	—	66	F10	PTB20	DISABLED		PTB20				FB_AD31	CMP0_ OUT		
—	—	—	67	F9	PTB21	DISABLED		PTB21				FB_AD30	CMP1_ OUT		
—	—	—	68	F8	PTB22	DISABLED		PTB22				FB_AD29			
—	—	—	69	E8	PTB23	DISABLED		PTB23		SPI0_ PCS5		FB_AD28			
D8	43	60	70	B9	PTC0	ADC0_ SE14	ADC0_ SE14	PTC0	SPI0_ PCS4	PDB0_ EXTRG	USB_ SOF_OUT	FB_AD14			
C6	44	61	71	D8	PTC1/ LLWU_P6	ADC0_ SE15	ADC0_ SE15	PTC1/ LLWU_P6	SPI0_ PCS3	UART1_ RTS_b	FTM0_ CH0	FB_AD13	I2S0_ TXD0	LPUART0 _RTS_b	
B7	45	62	72	C8	PTC2	ADC0_ SE4b/ CMP1_IN0	ADC0_ SE4b/ CMP1_IN0	PTC2	SPI0_ PCS2	UART1_ CTS_b	FTM0_ CH1	FB_AD12	I2S0_TX_ FS	LPUART0 _CTS_b	
C8	46	63	73	B8	PTC3/ LLWU_P7	CMP1_IN1	CMP1_IN1	PTC3/ LLWU_P7	SPI0_ PCS1	UART1_ RX	FTM0_ CH2	CLKOUT	I2S0_TX_ BCLK	LPUART0 _RX	
E3	47	64	74	—	VSS	VSS	VSS								
E4	48	65	75	—	VDD	VDD	VDD								
B8	49	66	76	A8	PTC4/ LLWU_P8	DISABLED		PTC4/ LLWU_P8	SPI0_ PCS0	UART1_ TX	FTM0_ CH3	FB_AD11	CMP1_ OUT	LPUART0 _TX	
A8	50	67	77	D7	PTC5/ LLWU_P9	DISABLED		PTC5/ LLWU_P9	SPI0_SCK	LPTMR0_ ALT2	I2S0_ RXD0	FB_AD10	CMP0_ OUT	FTM0_ CH2	
A7	51	68	78	C7	PTC6/ LLWU_ P10	CMP0_IN0	CMP0_IN0	PTC6/ LLWU_ P10	SPI0_ SOUT	PDB0_ EXTRG	I2S0_RX_ BCLK	FB_AD9	I2S0_ MCLK		
B6	52	69	79	B7	PTC7	CMP0_IN1	CMP0_IN1	PTC7	SPI0_SIN	USB_ SOF_OUT	I2S0_RX_ FS	FB_AD8			

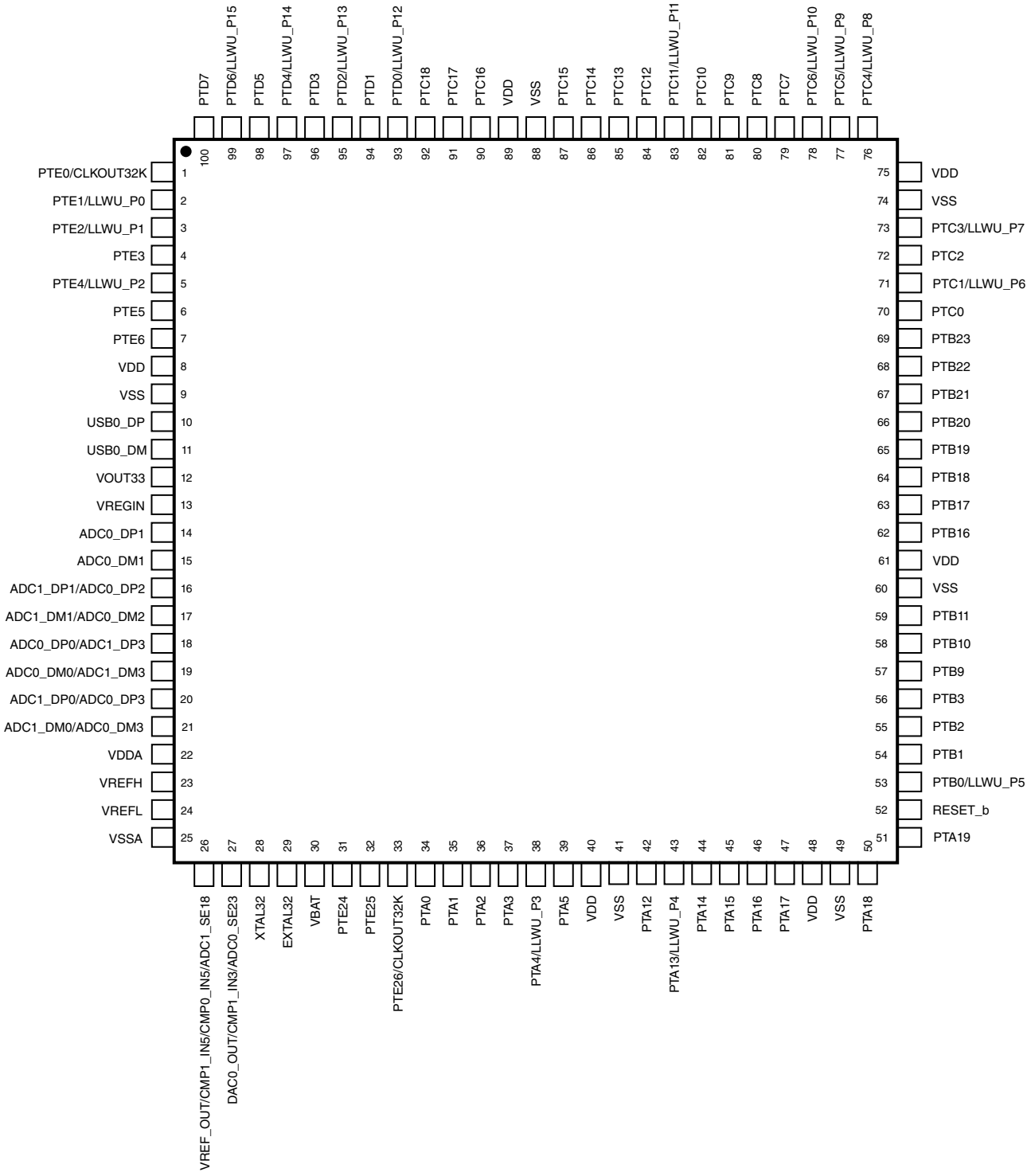

Figure 35. K22F 100 LQFP pinout diagram (top view)

	1	2	3	4	5	6	7	8	9	10	11	
A	PTD7	PTD5	PTD4/ LLWU_P14	PTC19	PTC14	PTC13	PTC8	PTC4/ LLWU_P8	PTD9	PTD8	NC	A
B	PTD10	PTD6/ LLWU_P15	PTD3	PTC18	PTC15	PTC12	PTC7	PTC3/ LLWU_P7	PTC0	PTB16	NC	B
C	PTD12	PTD11	PTD2/ LLWU_P13	PTC17	PTC11/ LLWU_P11	PTC10	PTC6/ LLWU_P10	PTC2	PTB19	PTB11	NC	C
D	PTD14	PTD13	PTD1	PTD0/ LLWU_P12	PTC16	PTC9	PTC5/ LLWU_P9	PTC1/ LLWU_P6	PTB18	PTB10	PTB8	D
E	PTD15	PTE2/ LLWU_P1	PTE1/ LLWU_P0	PTE0/ CLKOUT32K	VDD	VDD	VDD	PTB23	PTB17	PTB9	PTB7	E
F	USB0_DP	USB0_DM	PTE6	PTE3	VDDA	VSSA	VSS	PTB22	PTB21	PTB20	PTB6	F
G	VOUT33	VREGIN	VSS	PTE5	VREFH	VREFL	VSS	PTB3	PTB2	PTB1	PTB0/ LLWU_P5	G
H	ADC0_DP1	ADC0_DM1	ADC0_SE16/ CMP1_IN2/ ADC0_SE21	NC	PTE24	PTE26/ CLKOUT32K	PTE4/ LLWU_P2	PTA1	PTA3	PTA17	PTA29	H
J	ADC1_DP1/ ADC0_DP2	ADC1_DM1/ ADC0_DM2	ADC1_SE16/ ADC0_SE22	PTA11	PTE25	PTA0	PTA2	PTA4/ LLWU_P3	PTA10	PTA16	RESET_b	J
K	ADC0_DP0/ ADC1_DP3	ADC0_DM0/ ADC1_DM3	NC	DAC1_OUT/ CMP0_IN4/ ADC1_SE23	DAC0_OUT/ CMP1_IN3/ ADC0_SE23	VBAT	PTA5	PTA12	PTA14	VSS	PTA19	K
L	ADC1_DP0/ ADC0_DP3	ADC1_DM0/ ADC0_DM3	VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18	XTAL32	EXTAL32	VSS	RTC_ WAKEUP_B	PTA13/ LLWU_P4	PTA15	VDD	PTA18	L
	1	2	3	4	5	6	7	8	9	10	11	

Figure 36. K22F 121 XFBGA pinout diagram (transparent top view)

6 Part identification

6.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

Table 54. Revision History (continued)

Rev. No.	Date	Substantial Changes
		• Added the following footnote on maximum Fast mode value for SCL Clock Frequency: "The maximum SCL Clock Frequency in Fast mode with maximum bus loading can only be achieved when using the High drive pins across the full voltage range and when using the Normal drive pins and VDD ≥ 2.7 V." • Updated minimum Fast mode value for LOW period of the SCL clock to 1.25 µ • Added "I^2C 1 Mbps timing" table • Removed Section 6, "Ordering parts." • Specified that the figure, "K22F 64 LQFP Pinout Diagram" is a top view • Specified that the figure, "K22F 64 MAPBGA Pinout Diagram" is a transparent top view • Specified that the figure, "K22F 100 LQFP Pinout Diagram" is a top view • Corrected part marking shown in "64-pin MAPBGA part marking" table
4	7/2014	• In "Power consumption operating behaviors table": • Updated existing typical power measurements • Added new typical power measurements for the following: • IDD_HSRUN (High Speed Run mode current executing CoreMark code) • IDD_RUNCO (Run mode current in Compute operation, executing CoreMark code) • IDD_RUN (Run mode current in Compute operation, executing while(1) loop) • IDD_VLPR (Very Low Power mode current executing CoreMark code) • IDD_VLPR (Very Low Power Run mode current in Compute operation, executing while(1) loop) • In "Thermal attributes" table, added values for 64 MAPBGA package
3	5/2014	• In "Voltage and current operating ratings" table, updated maximum digital supply current • Updated "Voltage and current operating behaviors" table • Updated "Power mode transition operating behaviors" table • Updated "Power consumption operating behaviors" table • Updated "EMC radiated emissions operating behaviors for 64 LQFP package" table • Updated "Thermal attributes" table • Updated "MCG specifications" table • Updated "IRC48M specifications" table • Updated "16-bit ADC operating conditions" table • Updated "Voltage reference electrical specifications" section • Added "64-pin MAPBGA part marking" table
2	3/2014	Initial public release